



## Material Content Data Sheet



<b>Sales Product Name</b>		BFP 843F H6327		<b>Issued</b>		2. August 2018		
<b>MA#</b>		MA001094008						
<b>Package</b>		PG-TSFP-4-1		<b>Weight*</b>		1.87 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.001	0.04		376	
	noble metal	gold	7440-57-5	0.003	0.15		1457	
	inorganic material	silicon	7440-21-3	0.024	1.27	1.46	12704	14537
leadframe	inorganic material	silicon	7440-21-3	0.000	0.01		79	
	non noble metal	titanium	7440-32-6	0.001	0.04		394	
	non noble metal	chromium	7440-47-3	0.002	0.12		1183	
	non noble metal	copper	7440-50-8	0.734	39.26	39.43	392602	394258
wire	noble metal	gold	7440-57-5	0.007	0.35	0.35	3514	3514
encapsulation	organic material	carbon black	1333-86-4	0.010	0.51		5134	
	plastics	epoxy resin	-	0.206	11.04		110377	
	inorganic material	silicondioxide	60676-86-0	0.744	39.78	51.33	397870	513381
leadfinish	non noble metal	tin	7440-31-5	0.049	2.62	2.62	26171	26171
plating	noble metal	silver	7440-22-4	0.090	4.81	4.81	48139	48139
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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